



Session Title:	[WeC1] Advanced Bonding Technology
Session Date:	November 13 (Wed.), 2024
Session Time:	09:00-10:40
Session Room:	Room C (Grand Ballroom 3, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Gu-Sung Kim (Kangnam Univ., Korea)

[WeC1-1] [Plenary] 09:00-09:45

Surface Activated Bonding for 3D and Heterogeneous Integration Current Status and Future Prospects

Tadatomo Suga (Meisei Univ., Japan)

[WeC1-2] [Invited] 09:45-10:15

The Role of Hybrid Bonding in Modern Semiconductors

Thomas Glinsner (EV Group, Austria)

[WeC1-3] [Invited] 10:15-10:40

FINE Cut for HBM Wafer and FINE Forming for TVG of Glass Substrate

Seak-Joon Lee (ITI, Korea)